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AMENDMENTS TO THE CLAIMS

Listing of Claims:

5 Claim 1 (original) A capacitive acceleration sensor comprising:
 a non-single-crystal-silicon-based substrate;
 a polysilicon beam structure having a movable section, the
 movable section comprising a movable electrode;
 a polysilicon supporter positioned on the
10 non-single-crystal-silicon-based substrate for fixing the beam
 structure and forming a distance between the beam structure
 and the non-single-crystal-silicon-based substrate;
 a stationary electrode positioned on the
 non-single-crystal-silicon-based substrate and opposite to the
15 movable section of the beam structure, the stationary
 electrode and the movable electrode constituting a plate
 capacitor; and
 a thin film transistor (TFT) control circuit positioned on the
 non-single-crystal-silicon-based substrate and electrically
20 connected to the plate capacitor.

Claim 2 (original) The capacitive acceleration sensor of claim 1 wherein
the non-single-crystal-silicon-based substrate is a glass
substrate.

25 Claim 3 (original) The capacitive acceleration sensor of claim 2 wherein
the TFT control circuit is a low temperature polysilicon TFT
control circuit.

30 Claim 4 (original) The capacitive acceleration sensor of claim 1 wherein
the non-single-crystal-silicon-based substrate is a quartz
substrate.

Claim 5 (original) The capacitive acceleration sensor of claim 4 wherein the TFT control circuit is a high temperature polysilicon TFT control circuit.

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Claim 6 (original) The capacitive acceleration sensor of claim 1 wherein the stationary electrode comprises aluminum (Al), titanium (Ti), platinum (Pt), or alloys.

10 Claim 7 (original) The capacitive acceleration sensor of claim 1 wherein the beam structure and the supporter are formed simultaneously.

Claim 8 (cancelled)

15 Claim 9 (original) The capacitive acceleration sensor of claim 1 wherein the movable electrode comprises doped polysilicon or a conductive material.

20 Claim 10 (currently amended) The capacitive acceleration sensor of claim 1 wherein the non-single-crystal-silicon-based substrate further comprises a thin film transistor display region for displaying a variation of pressure detected by the capacitive acceleration sensor.

25 Claim 11 (currently amended) A capacitive acceleration sensor comprising:

an insulating substrate;

a cantilever beam structure positioned on the insulating substrate having a movable section, the movable section comprising a movable electrode;

30 a stationary electrode positioned on the insulating substrate and opposite to the movable section of the cantilever beam structure, the stationary electrode and the movable

electrode constituting a plate capacitor; and
a thin film transistor control circuit positioned on the
insulating substrate and electrically connected to the
plate capacitor.

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Claim 12 (original) The capacitive acceleration sensor of claim 11
wherein the stationary electrode comprises aluminum (Al),
titanium (Ti), platinum (Pt), or alloys.

10 Claim 13 (original) The capacitive acceleration sensor of claim 11
wherein the cantilever beam structure comprises polysilicon.

15 Claim 14 (original) The capacitive acceleration sensor of claim 11
wherein the movable electrode comprises doped polysilicon or
a conductive material.

Claim 15 (original) The capacitive acceleration sensor of claim 11
wherein the insulating substrate is a glass substrate.

20 Claim 16 (currently amended) The capacitive acceleration sensor of
claim 15 wherein the thin film transistor control circuit is
positioned on the glass substrate and the thin film transistor
control circuit ~~comprises~~ is a low temperature polysilicon thin
film transistor control circuit.

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Claim 17 (original) The capacitive acceleration sensor of claim 11
wherein the insulating substrate is a quartz substrate.

30 Claim 18 (currently amended) The capacitive acceleration sensor of
claim 17 wherein the thin film transistor control circuit is
positioned on the quartz substrate and the thin film transistor
control circuit ~~comprises~~ is a high temperature polysilicon

thin film transistor control circuit.

Claim 19 (cancelled)

5 Claim 20 (currently amended) The capacitive acceleration sensor of claim 11 wherein the thin film transistor control circuit is positioned on a ~~flexible printed circuit (FPC) board~~, the control circuit being electrically connected to the plate capacitor via the a flexible printed circuit (FPC) board.

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Claim 21 (currently amended) The capacitive acceleration sensor of claim 11 wherein the insulating substrate further comprises a thin film transistor display region for displaying a variation of pressure detected by the capacitive acceleration sensor.

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